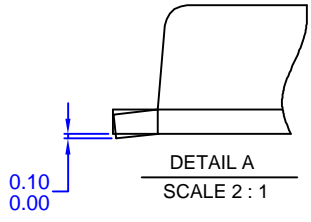
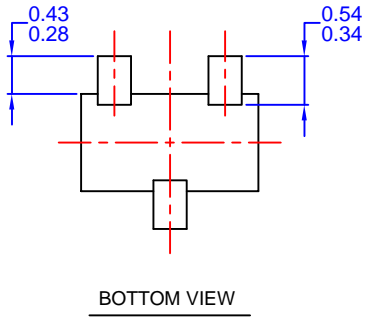
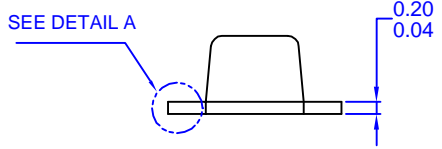
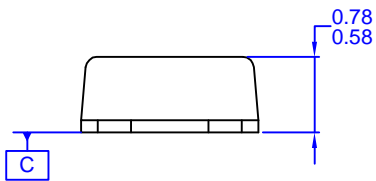
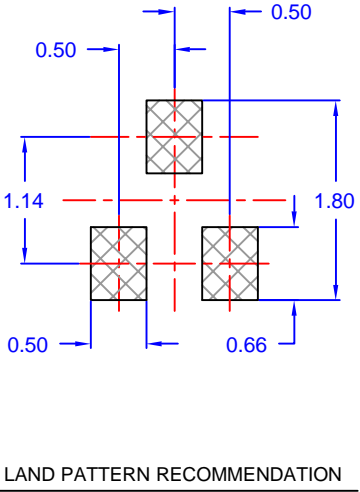
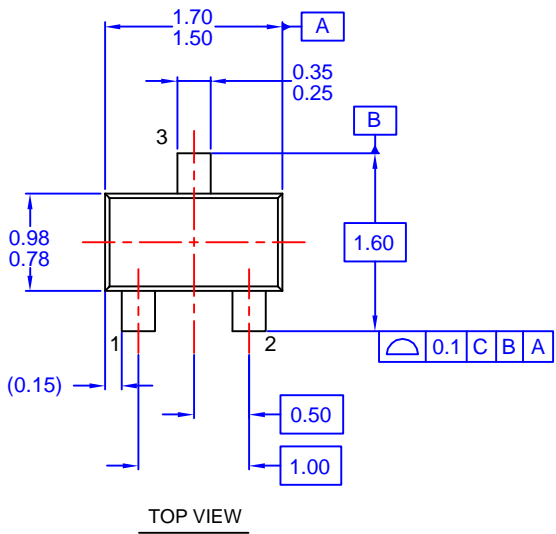


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REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APPD
A	RELEASE TO DOCUMENT CONTROL	-	8AUG05	OS.JEON



- NOTES:
- A) THIS PACKAGE CONFORMS TO EIAJ SC89 PACKAGING STANDARD.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DRAWING CONFORMS TO ASME Y14.5M-1994
 - D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

MAD03ArevA

APPROVALS		DATE	FAIRCHILD BUCHEON KOREA SEMICONDUCTOR™	
DRAWN	S. W LIM	8AUG05		
DFTG. CHK.	J. S SON	8AUG05	3LD, SC89, EIAJ-SC89, 1.2MM WIDE, SOT523F	
ENGR. CHK.	O. S JEON	8AUG05		
PROJECTION			SCALE	1:1
INCH (MM)			SIZE	N/A
			DRAWING NUMBER	MKT-MAD03A
			REV	A
			FORMERLY: N/A	SHEET: 1 OF 1